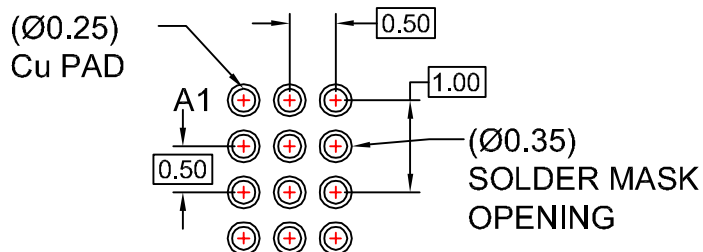
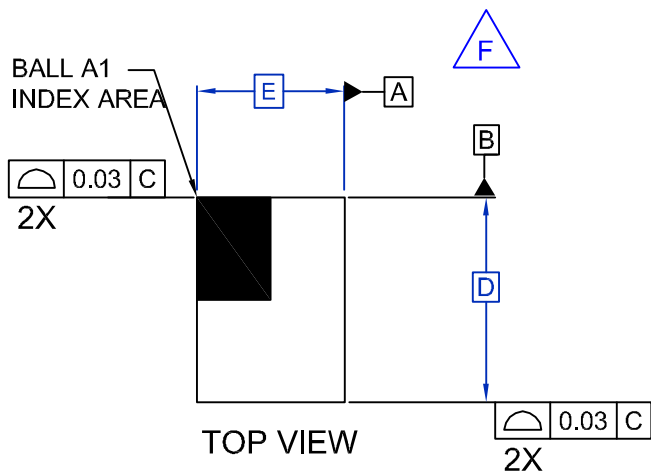
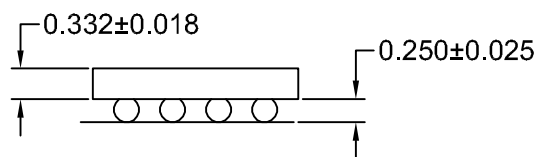
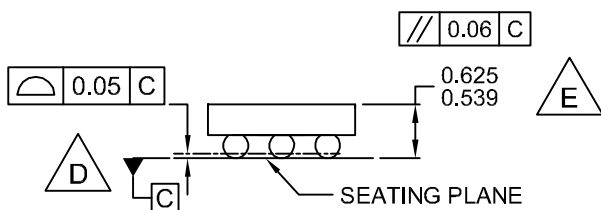


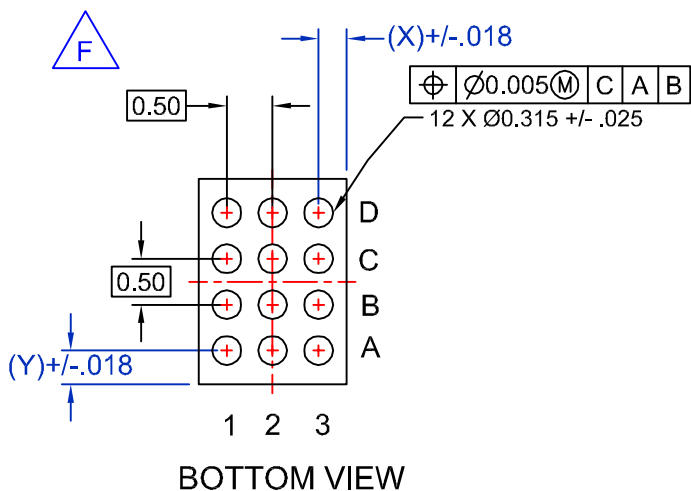
REVISIONS			
REV	DESCRIPTION	DATE	BY/APPD
0	Initial drawing release.		H. Allen
0	Removed line showing lamination.	9-10-2007	S. Martin
1	Removed note on typical thickness, renumbered other notes, added min dimension on thickness, release to Documentum.	9-12-2007	S. Martin
2	Added missing Note E, specifying thickness range.	2-19-2008	L. England



RECOMMENDED LAND PATTERN (NSMD)



SIDE VIEWS



BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 582 MICRONS ± 38 MICRONS (539-625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

G. DRAWING FILENAME: MKT-UC012AArev2

FSC Internal Note:  
- Type 1 WL CSP provided by Amkor only.

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™		
DRAWN L. England	2-19-2008	333 Western Ave. So. Portland, Maine, USA		
DFTG. CHK. S. Martin	12-19-2008	12BALL TYPE 1 WL-CSP, 3X4 ARRAY 0.5MM PITCH, 300UM BALL		
ENGR. CHK.		SCALE N/A	SIZE N/A	DRAWING NUMBER MKT-UC012AA
		REV 2	DO NOT SCALE DRAWING	
		SHEET 1 of 1		